



IEEE AIPS

February 23–24, 2027
Austin, Texas, USA
IEEE Congress on AI for Physical Systems



CALL FOR POSTERS

The IEEE Congress on AI for Physical Systems (AIPS), co-sponsored by the IEEE UFFC Society, Sensors Council, and MEMS Technical Community, invites poster submissions for its inaugural meeting on February 23–24, 2027, at the University of Texas at Austin.

AIPS is a forum for AI that works with real physical systems relevant to fields covered across UFFC, Sensors, and MEMS, including materials and devices, fabrication and metrology, system integration and packaging, market/application-specific operation. We seek posters in two main streams: AI enabling new opportunities and performance enhancement for technologies across different applications and fields, and AI that changes how research and development are performed, accelerating discovery, design, fabrication, and testing.

Academic, industry, government, and clinical researchers are all invited. Topics include, but are not limited to:

- » AI-driven discovery and design of materials, including piezoelectrics, ferroelectrics, and nanoscale materials
- » AI-assisted design, modeling, and simulation of devices and systems
- » AI for fabrication, manufacturing, and metrology, including digital twins
- » Sensor fusion, edge AI, and embedded intelligence
- » Physical devices and hardware for AI, including timing, frequency control, and neuromorphic computing
- » AI for imaging, sensing, and signal processing, including medical ultrasound and nondestructive testing
- » AI-enabled applications in healthcare, robotics, wearables, and autonomous systems
- » Data, benchmarks, reliability, and uncertainty in AI for physical systems
- » Safety and security in AI for physical systems
- » Education, workforce development, and ethics

IMPORTANT DATES

Submission Deadline

December 31, 2026

Acceptance Announcement

January 15, 2027

ORGANIZING COMMITTEE

General Chair

Wan-Thai Hsu

Soundskrit

Program Chair

Dana Weinstein

Purdue University

Local Arrangement Chair

Ruochen Lu

University of Texas, Austin

Society Leaders

Debra Coler

Tablerock Consulting Solutions LLC,
President of IEEE UFFC

Anil Roy

Plaksha University, President of IEEE
Sensor Council

Clark Nguyen

UC Berkeley, President of IEEE MEMS
Technical Community

Committee Members

Aaron Partridge

SiTime

Chun Zhao

University of York

Jan D'hooge

KU Leuven

Steven Freear

University of Leeds

Rolland Vida

Budapest University of Technology
and Economics

Jeronimo Segovia-Fernandez

Texas Instrument

Mark Schafer

Rockefeller Neuroscience Institute,
WVU

Ruud van Sloun

Eindhoven University of Technology

Serge Dos Santos

INSA Centre Val de Loire (INSA-CVL)

Dean Ta

Fudan University

Rama K. Vasudevan

Oak Ridge National Laboratory

Zuo-Guang Ye

Simon Fraser University